

【書類名】 図面

【図1】 Fig.1

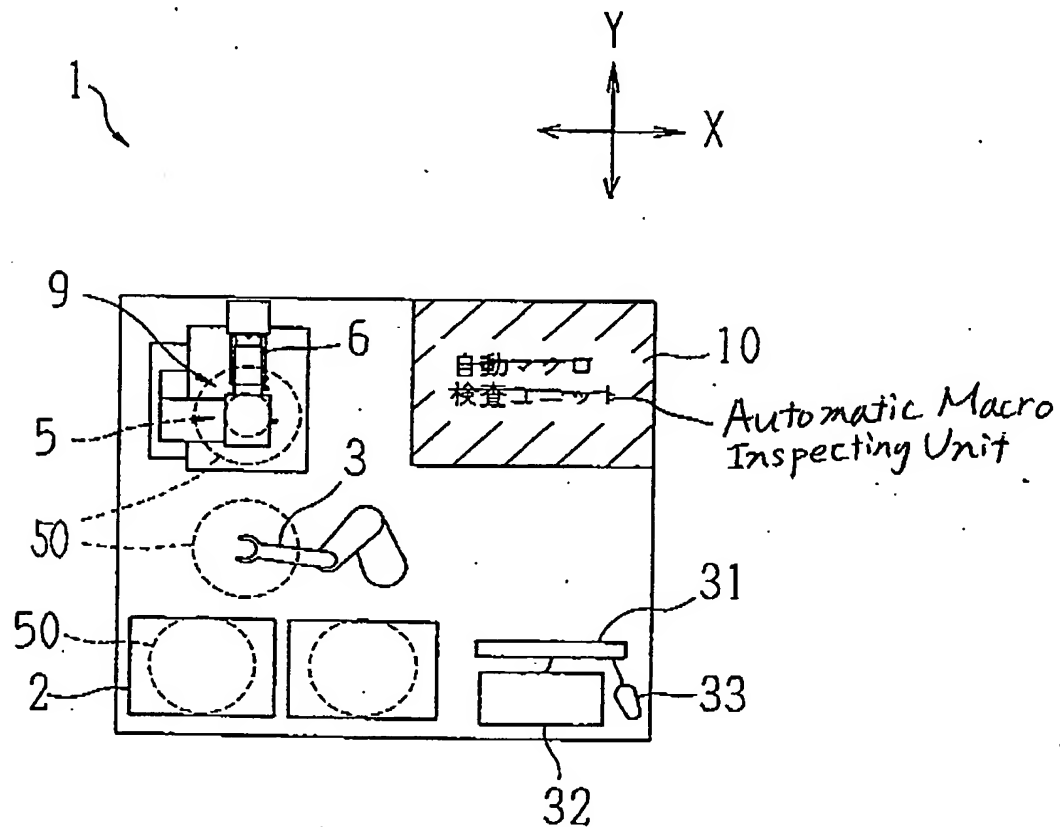
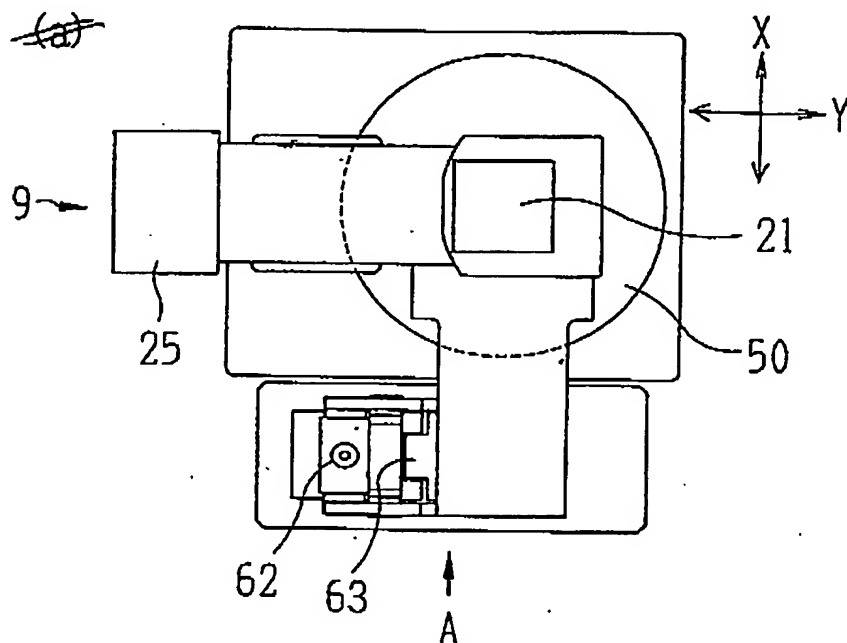
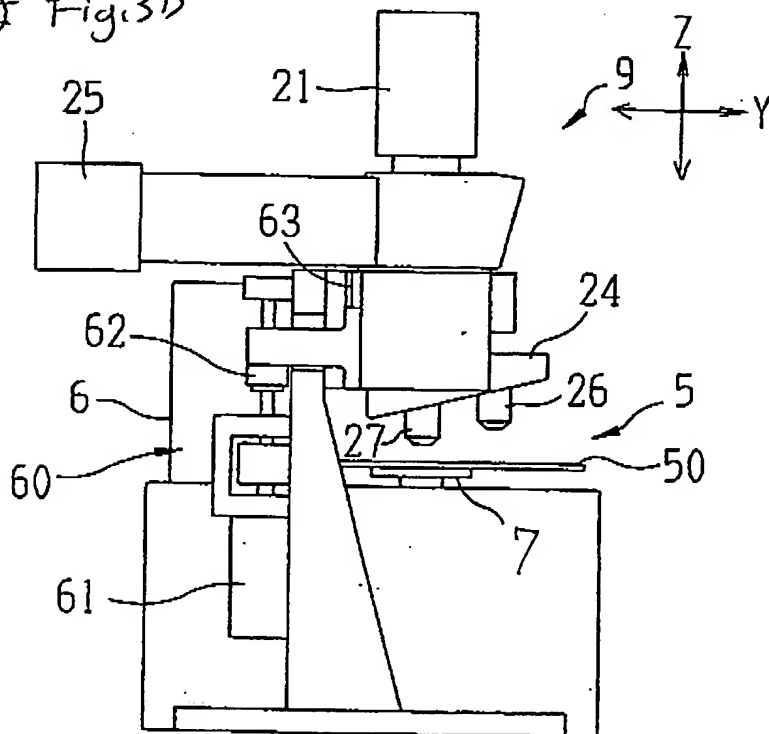


図3A Fig.3A

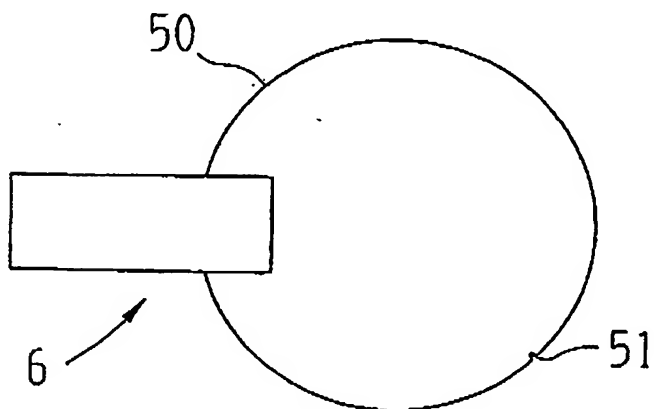


(b) Fig.3B



(図4)

(a) Fig. 4A



(b) Fig. 4B

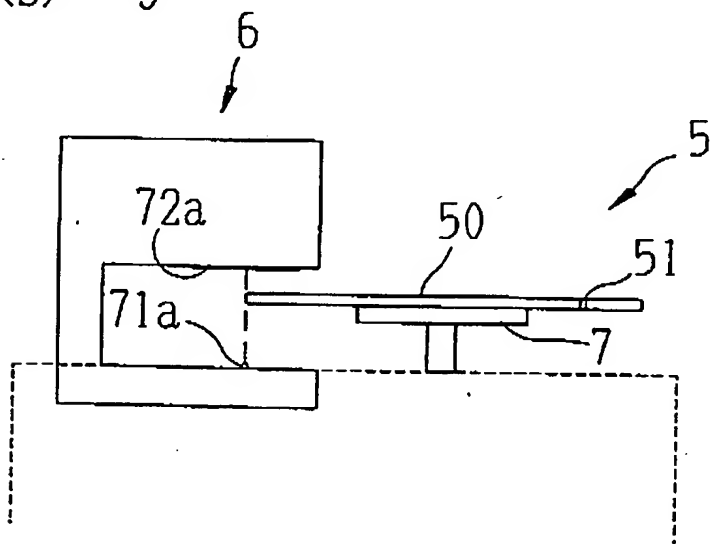


図5

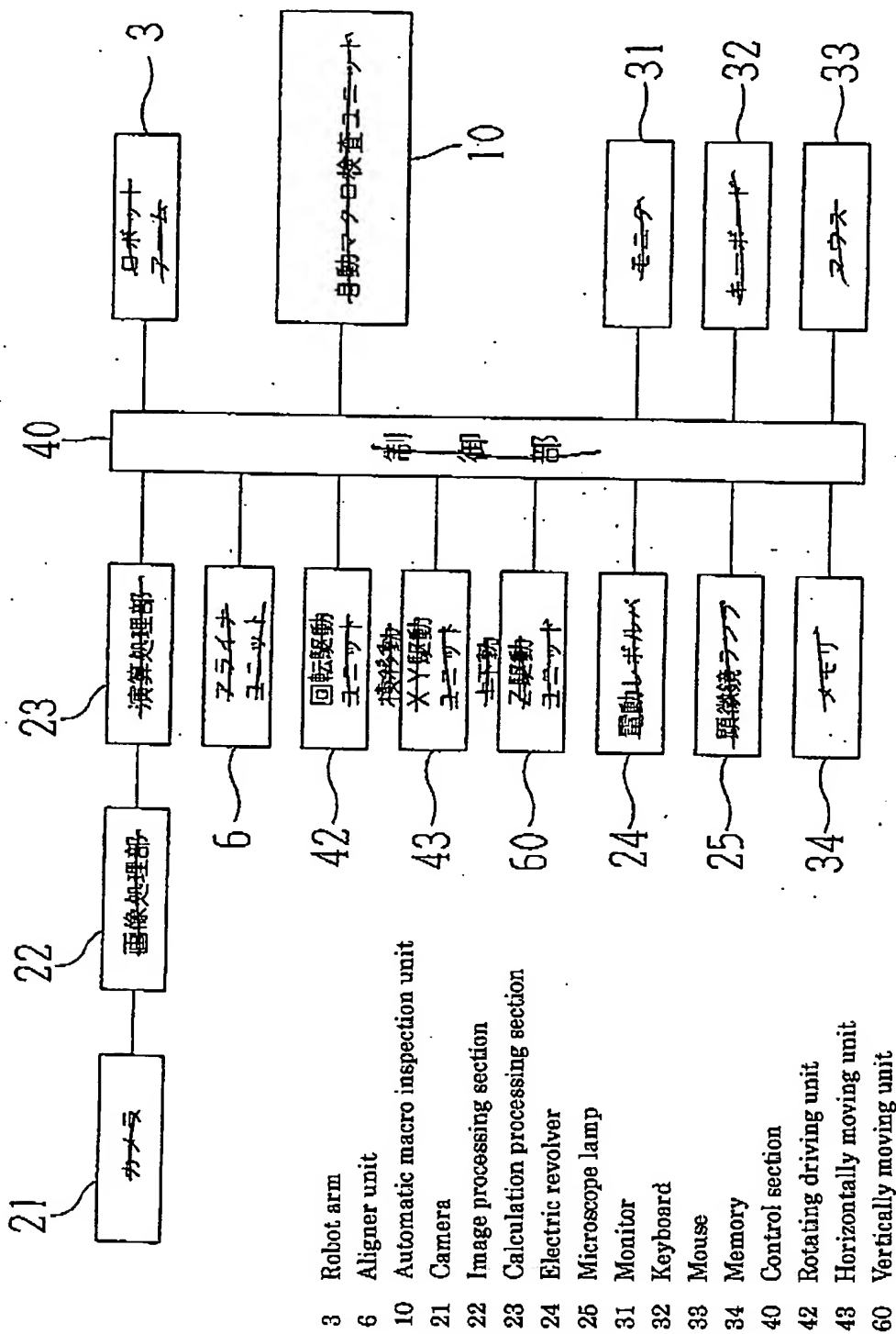


Fig.5

Start

S1 Input inspecting conditions (drawing stage, type number and manufacturing process).

S2 Start inspection.

55 Convey water from carrier to mounting table with robot arm.

S4 Rotate mounting table.

53 Detect notch or orientation flat position and center position with aligner unit.

50 Adjust notch or orientation flat position to predetermined position (direction)
with rotating unit.

S7 Correct eccentricity of wafer with horizontally moving unit and move wafer to a predetermined inspecting position.

S8 Light microscope lamp at predetermined brightness.

22 rotate electric revolver to set magnification of objective lens at 2.5 times.

310 Move microscope unit in direction Z to adjust focus.

lake photograph of water and process photographed image.

S12 Confirm and extract mask ID image by pattern matching.

Move water with horizontally moving unit. (Position by inching.)

S14 Light microscope lamp at predetermined brightness.

rotate electric revolver to set magnification of objective lens at 20 times.

S16 Move microscope unit in direction Z to adjust focus.

Take photograph of mask ID and conduct image processing.

518 Confirm mask ID by pattern matching.

S19 Does mask ID agree?

3520 Convey wafer to automatic macro inspecting unit with robot arm.

Conduct inspection with automatic macro inspecting unit.

522 Return wafer to carrier with robot arm.

Display result of inspection on monitor.

324 End

25 Return wafer to carrier with robot arm.

26 **Display result of inspection on monitor.**

27 End

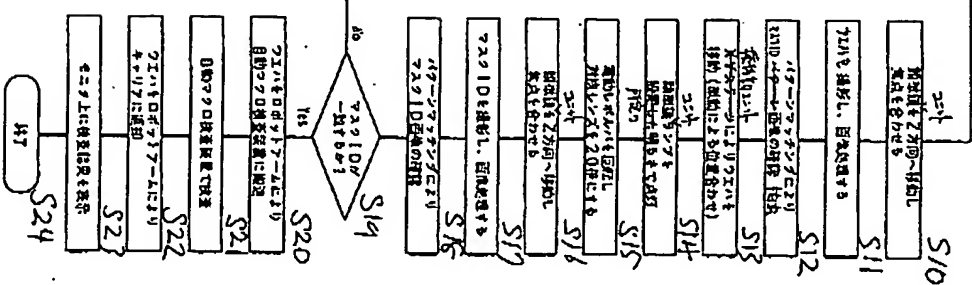


図7

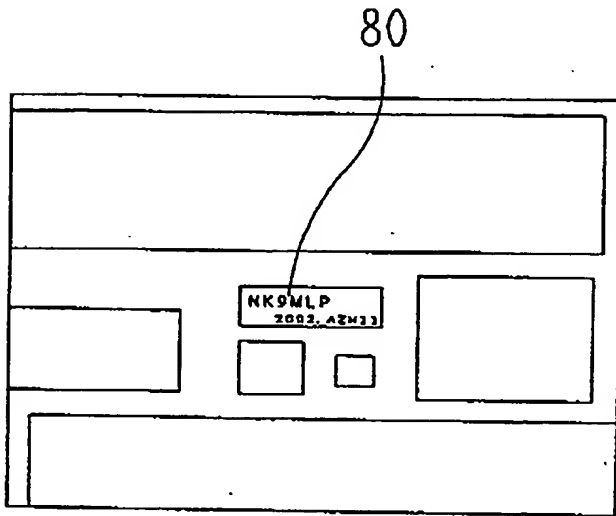


Fig. 7

図8

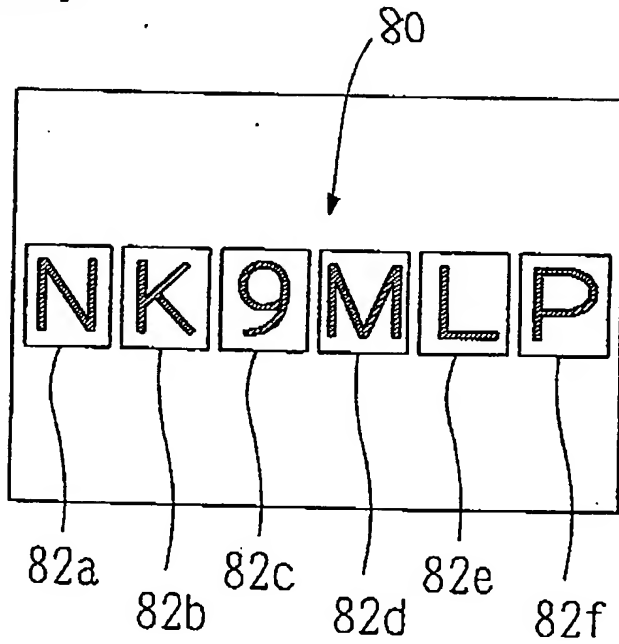
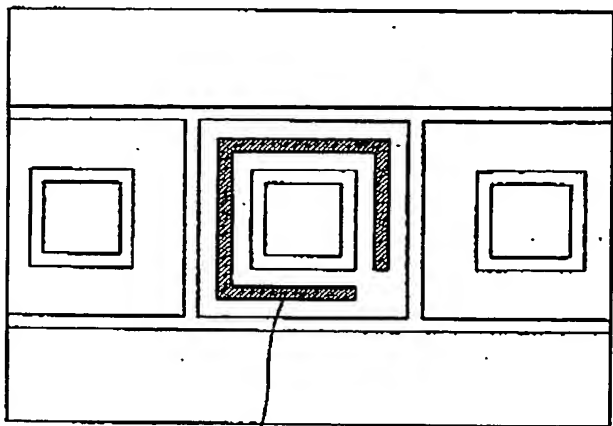


Fig. 8

【図9】

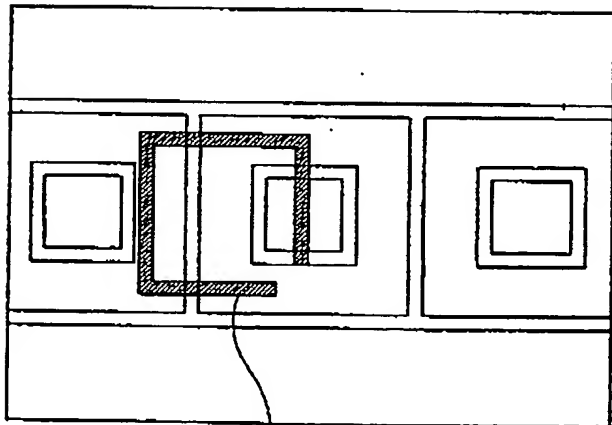
(a)



90

Fig. 9A

(b)



90°

Fig. 9B